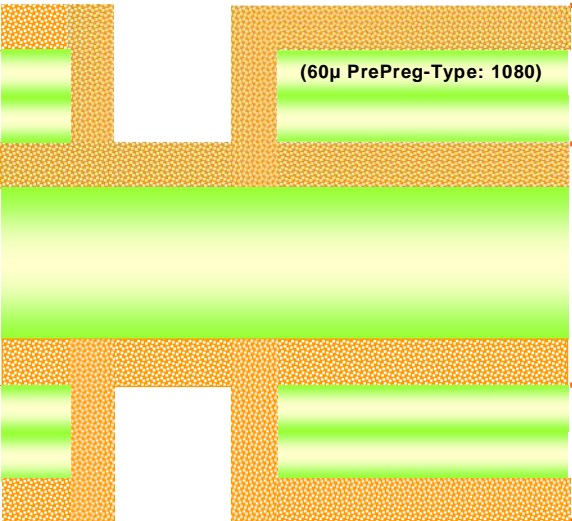
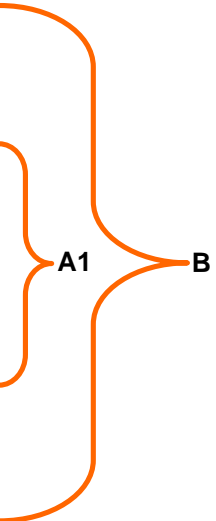


**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
04	146	FR4	35	L110.35	P06	(Blind Vias 01 to 02 und 99 to 3)

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_146\_FR4\_35\_L110.35\_p06\_v1-2\_99-3**

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	35 $\mu$	Copper		
	60 $\mu$	Prepreg		
Layer-2	60 $\mu$	Prepreg		
	35 $\mu$	Copper		
Layer-3	1100 $\mu$	L-FR4		
	35 $\mu$	Copper		
Layer-99	60 $\mu$	Prepreg		
	35 $\mu$	Copper		

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